

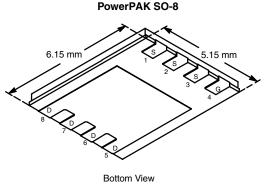
### New Product

# Si7491DP

Vishay Siliconix

## P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
- 30	0.0085 at V <sub>GS</sub> = - 10 V	– 18			
	0.013 at V <sub>GS</sub> = $-4.5$ V	- 14			



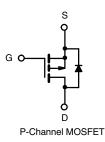
### Ordering Information: Si7491DP-T1 Si7491DP-T1—E3 (Lead (Pb)-free)

### FEATURES

- TrenchFET<sup>®</sup> Power MOSFETS
- New Low Thermal Resistance PowerPAK<sup>®</sup> Package with Low 1.07-mm Profile

### **APPLICATIONS**

- Battery and Load Switching
  - Notebook and Tablet Computers
  - Notebook and Tablet Battery Packs



<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \degree C$ , unless otherwise noted									
Parameter	Symbol	10 secs	Steady State	Unit					
Drain-Source Voltage		V <sub>DS</sub>	- 30		V				
Gate-Source Voltage		V <sub>GS</sub>	± 20						
Continuous Drain Current (T 150 °C) <sup>8</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	- 18	- 11	А				
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		- 14	- 8					
Pulsed Drain Current		I <sub>DM</sub>	- 50		A				
Continuous Source Current (Diode Conduction) <sup>a</sup>	ا <sub>S</sub>	- 4.5	- 1.6						
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	PD	5	1.8	W				
Maximum Power Dissipation*	T <sub>A</sub> = 70 °C	'D	3.2	1.1	~~				
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	– 55 to 150		°C				
Soldering Recommendations (Peak Temperature) <sup>b,c</sup>			260						

#### THERMAL RESISTANCE RATINGS Parameter Symbol Typical Maximum Unit $t \le 10$ sec 20 25 Maximum Junction-to-Ambient<sup>a</sup> R<sub>thJA</sub> 54 68 Steady State °C/W Maximum Junction-to-Case (Drain) Steady State R<sub>thJC</sub> 1.7 2.2

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.



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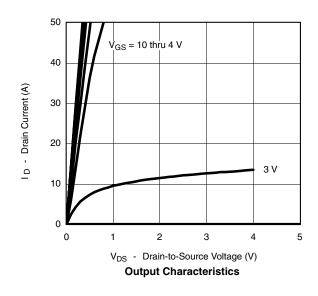


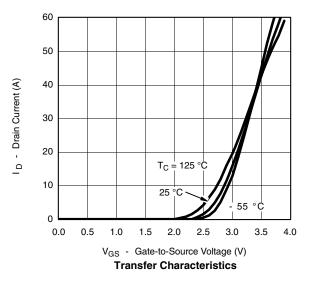
<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted										
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit				
Static					•					
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \ \mu A$	- 1.0		- 3.0	V				
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA				
	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μA				
Zero Gate Voltage Drain Current		$V_{DS}$ = - 30 V, $V_{GS}$ = 0 V, $T_J$ = 70 °C			- 10					
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = -5 V, V_{GS} = -10 V$	- 30			А				
	_	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -18 \text{ A}$		0.007	0.0085					
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -14 \text{ A}$		0.0105	0.013	Ω				
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -18 \text{ A}$		46		S				
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	$I_{S} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.74	- 1.1	V				
Dynamic <sup>b</sup>										
Total Gate Charge	Qg			56	85					
Gate-Source Charge	Q <sub>gs</sub> Q <sub>gd</sub>	$V_{DS} = -15$ V, $V_{GS} = -5$ V, $I_{D} = -18$ A		12		nC				
Gate-Drain Charge				25						
Turn-On Delay Time	t <sub>d(on)</sub>			150	225					
Rise Time	t <sub>r</sub>	$V_{DD}$ = − 15 V, R <sub>L</sub> = 15 Ω $I_D$ ≅ − 1 A, $V_{GEN}$ = − 4.5 V, R <sub>G</sub> = 6 Ω		190	290					
Turn-Off Delay Time	t <sub>d(off)</sub>			120	180					
Fall Time	t <sub>f</sub>	t <sub>f</sub>		90	140	ns				
Gate Resistance	R <sub>g</sub>			2.5						
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	$I_F = -2.9 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	l l	50	80					

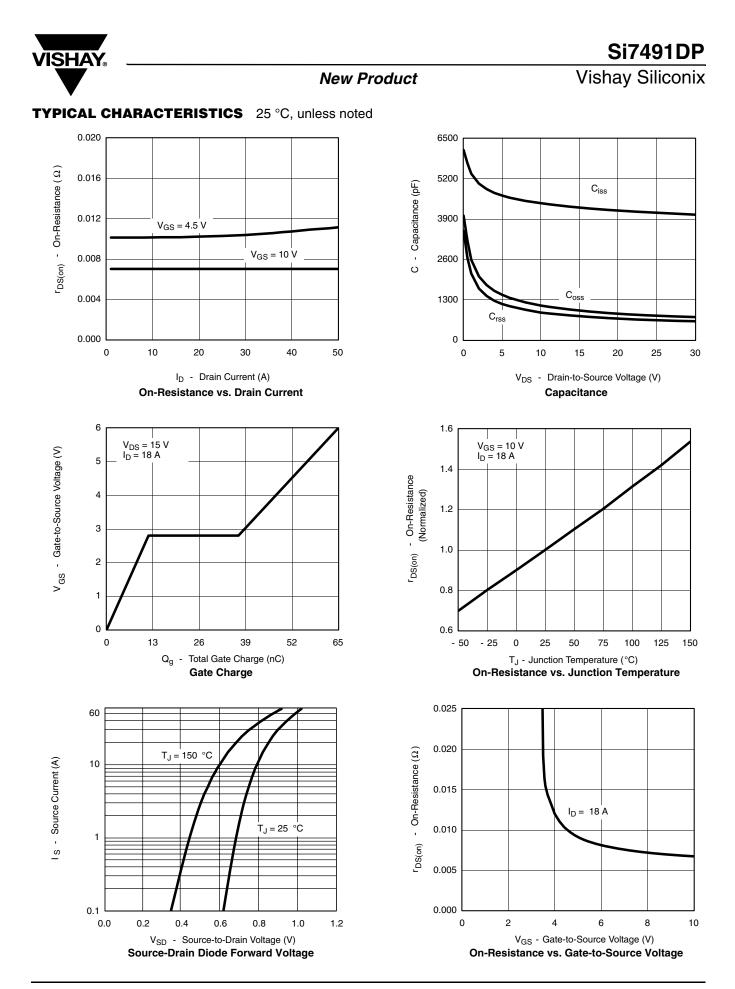
Notes a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### TYPICAL CHARACTERISTICS 25 °C, unless noted





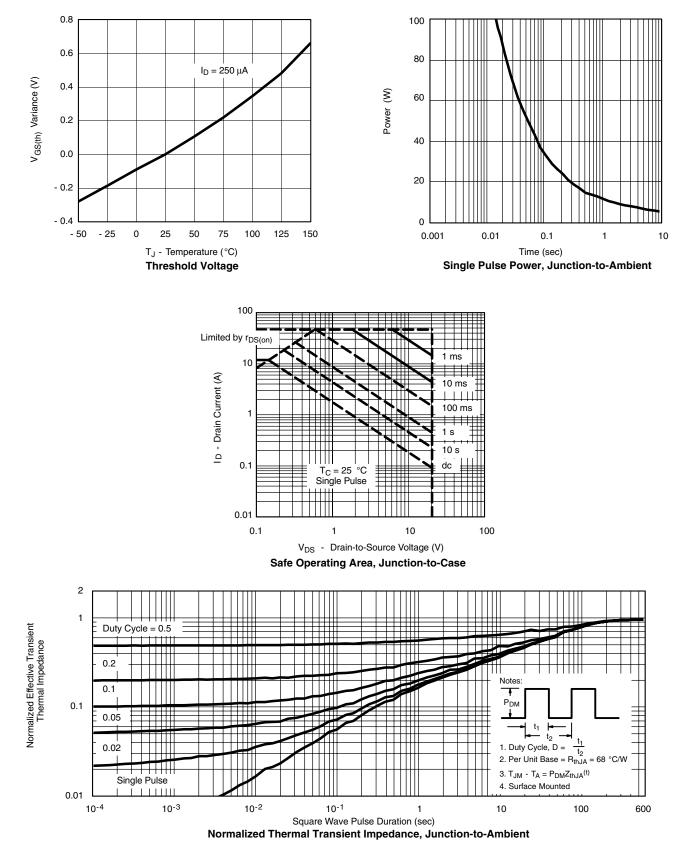


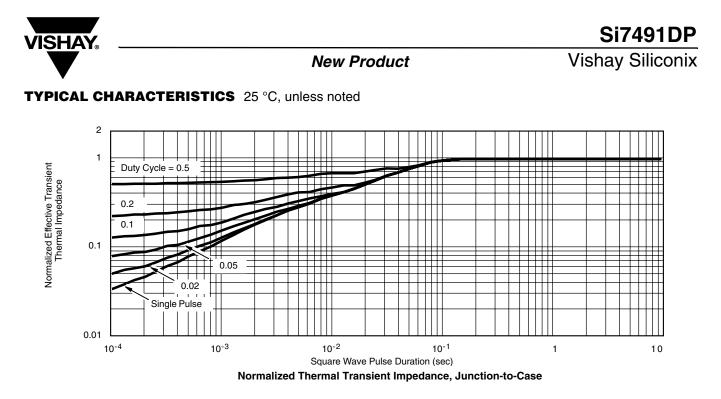
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Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72276.



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